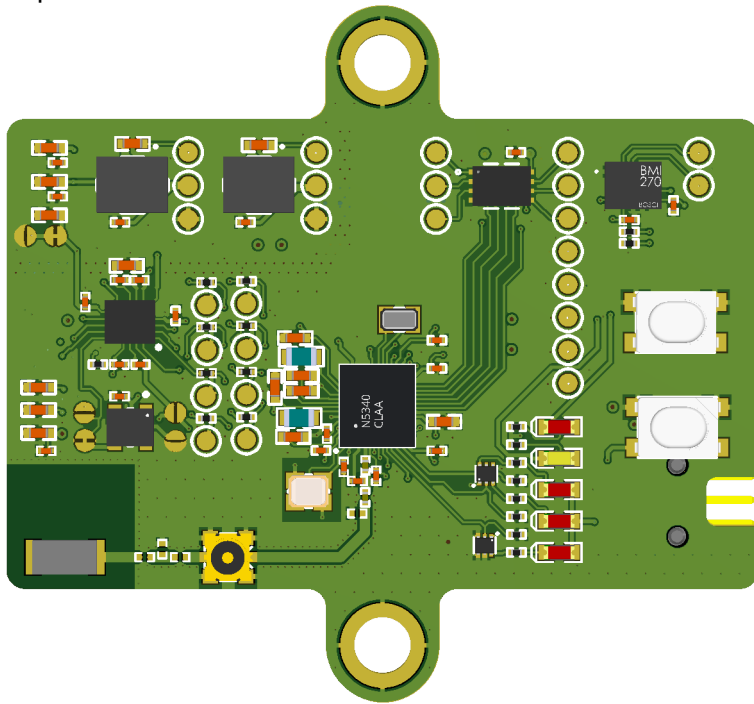
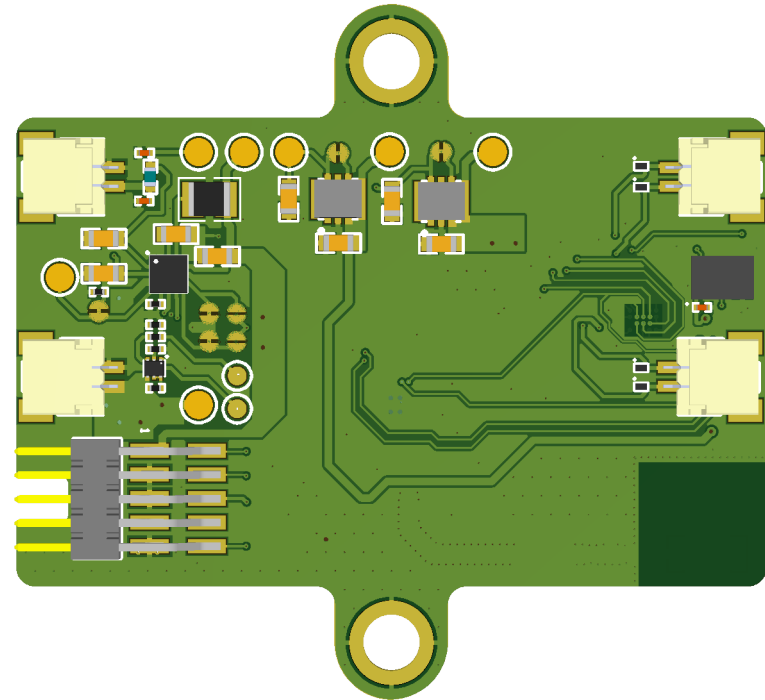


Tiresias Hearing Device Prototype - Hardware Documentation

Top View



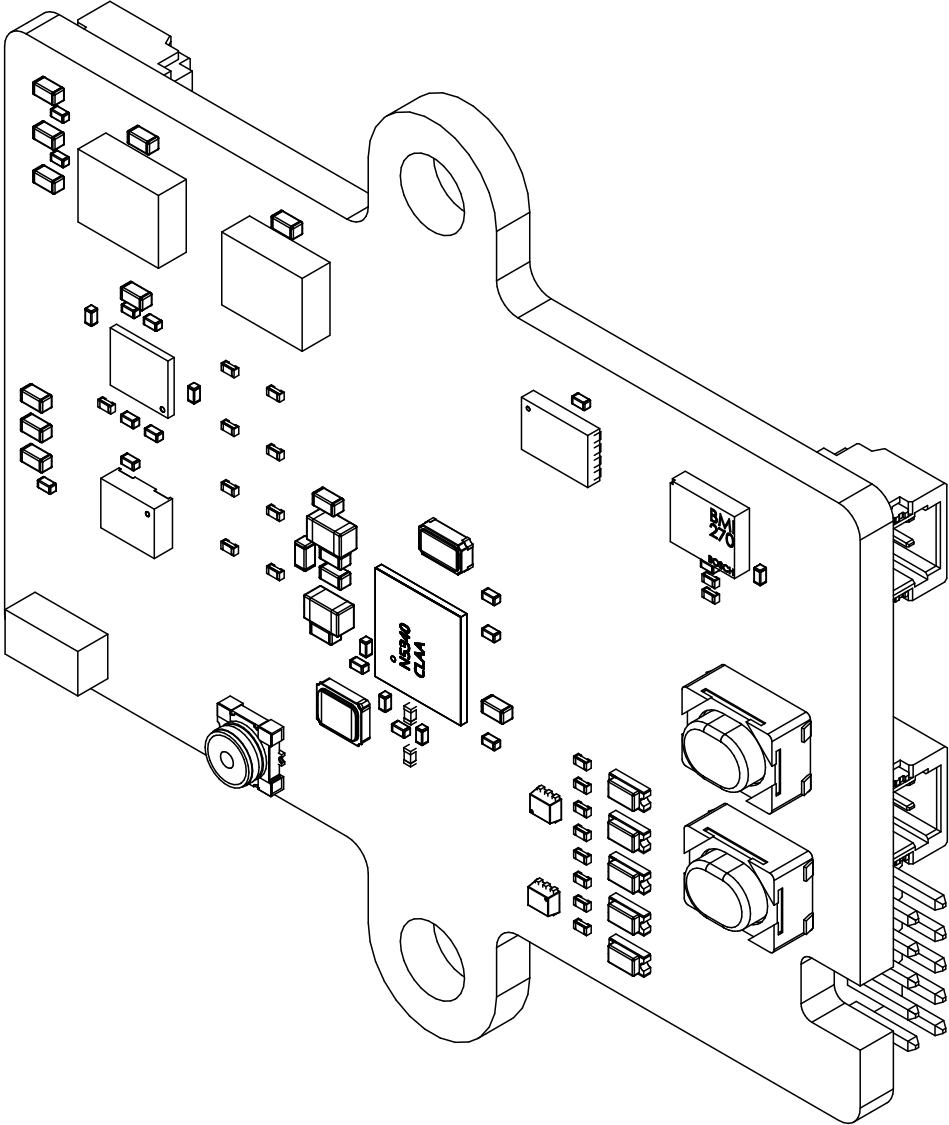
Bottom View



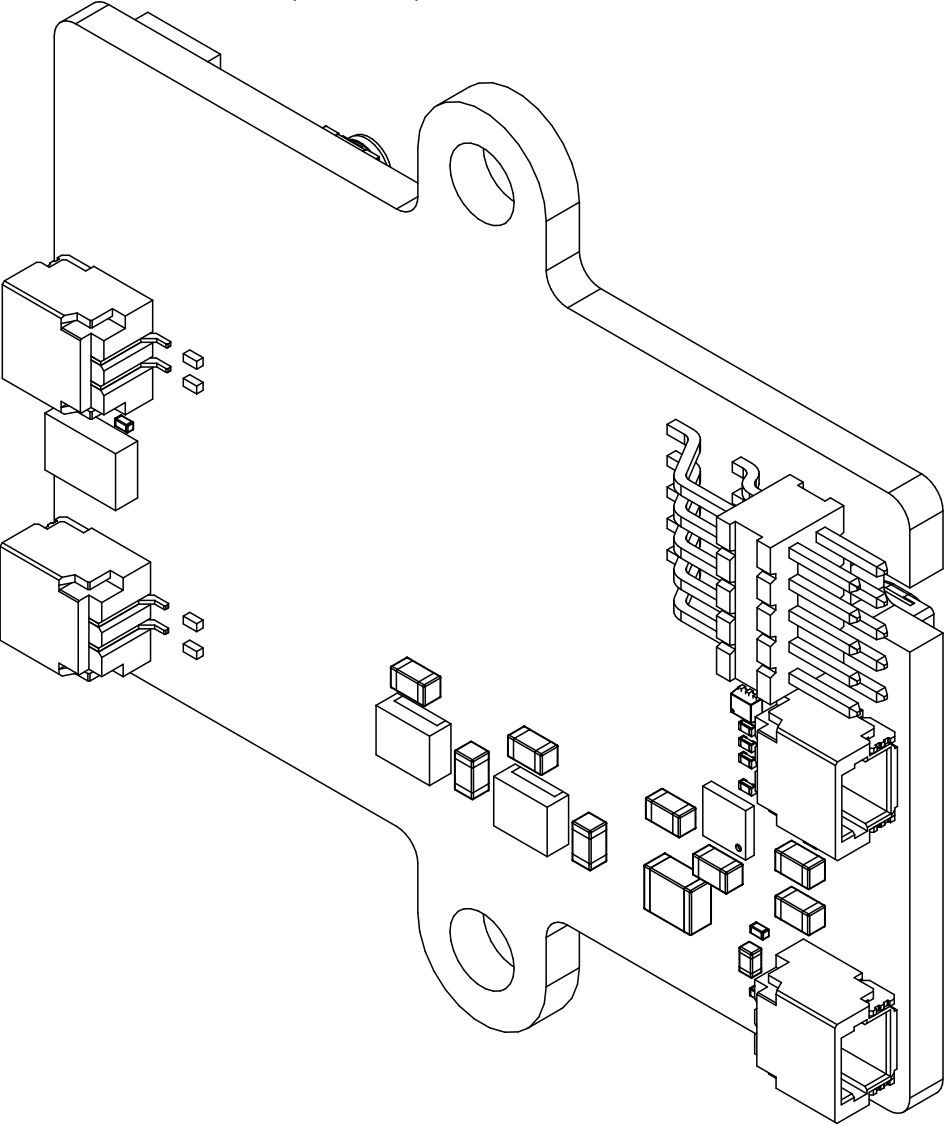
Engineer: João Victor Colombari Carlet

ISO View

View from Top side (Scale 4:1)



View from Bottom side (Scale 4:1)















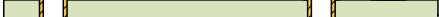







Stack-Up and Impedance

Transmission Line Structure Table

Impedance Id	Transmission Line	Target Impedance	Calculated Impedance	Trace layer	Wide Trace Width	Narrow Trace Width	Reference layers	Substack	Clearance	Target Tolerance
1	Coated Coplanar Waveguide With Ground	50	49.99	Top Layer	0.55mm	0.55mm	Int4 (GND)	Board Layer Stack	0.13mm	10%
2	Coated Coplanar Waveguide With Ground	50	49.99	Bottom Layer	0.55mm	0.55mm	Int1 (GND)	Board Layer Stack	0.13mm	10%

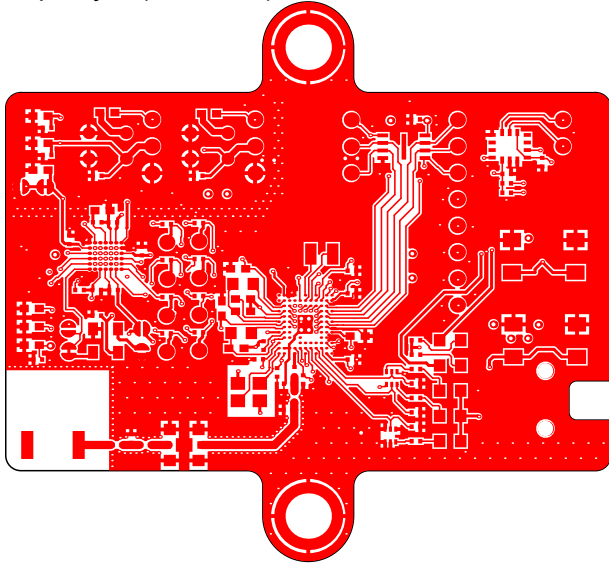
Layer Stack Legend

	Material	Layer	Thickness	Dielectric Material	Type	Gerber
		Top Overlay			Legend	GTO
	Surface Material	Top Solder	0.03mm	SM-002	Solder Mask	GTS
	Nickel, Gold	Top Surface Finish	0.00mm		Surface Finish	
	CF-004	Top Layer	0.04mm		Signal	GTL
	Prepreg		0.07mm	PP-006	Dielectric	
	Prepreg		0.07mm	PP-006	Dielectric	
	CF-004	Int1 (GND)	0.04mm		Signal	G1
	Core		0.46mm	Core-035	Dielectric	
	CF-004	Int2 (PWR)	0.04mm		Signal	G2
	Prepreg		0.07mm	PP-006	Dielectric	
	Prepreg		0.07mm	PP-006	Dielectric	
	CF-004	Int3 (SIG)	0.04mm		Signal	G3
	Core		0.46mm	Core-035	Dielectric	
	CF-004	Int4 (GND)	0.04mm		Signal	G4
	Prepreg		0.07mm	PP-006	Dielectric	
	Prepreg		0.07mm	PP-006	Dielectric	
	CF-004	Bottom Layer	0.04mm		Signal	GBL
	Nickel, Gold	Bottom Surface Finish	0.00mm		Surface Finish	
	Surface Material	Bottom Solder	0.03mm	SM-002	Solder Mask	GBS
		Bottom Overlay			Legend	GBO

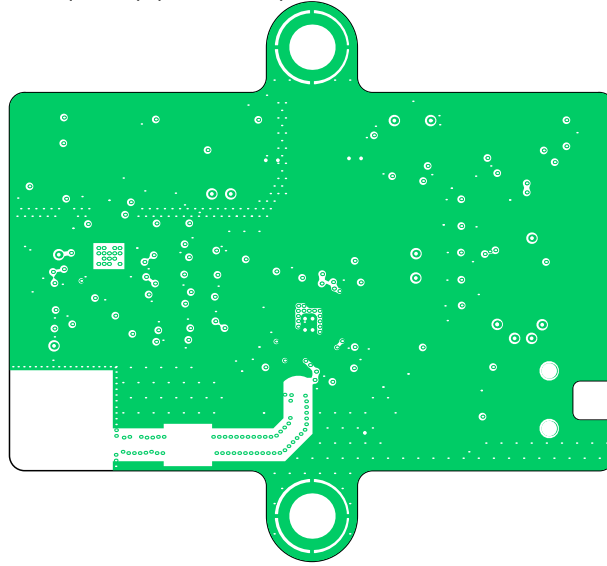
Total thickness: 1.61mm

Layers

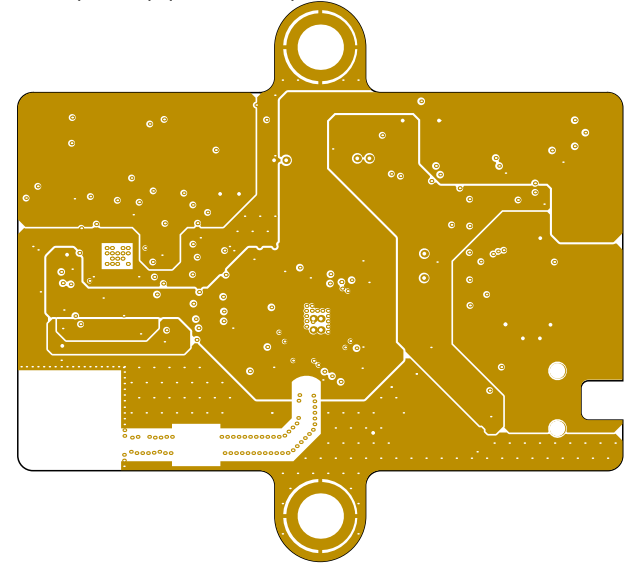
Top Layer (Scale 2:1)



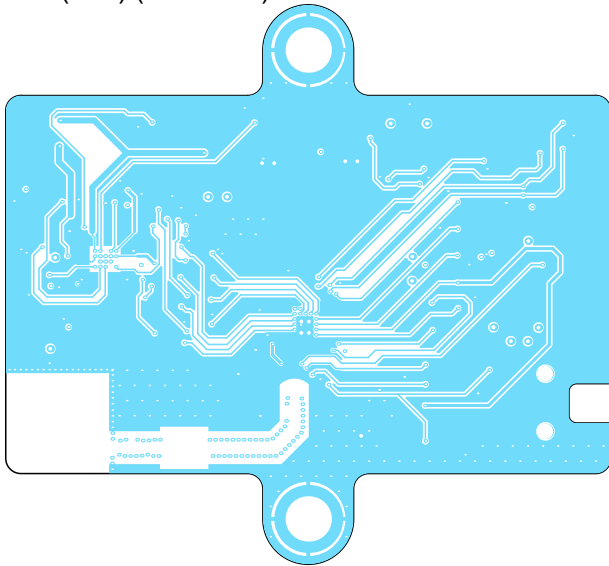
Int1 (GND) (Scale 2:1)



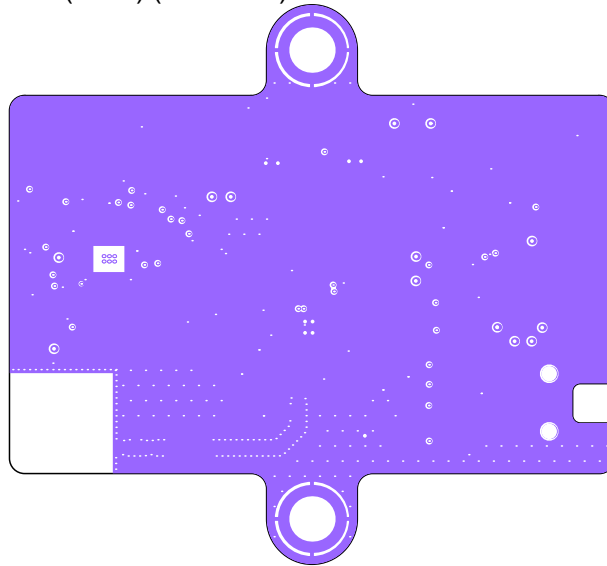
Int2 (PWR) (Scale 2:1)



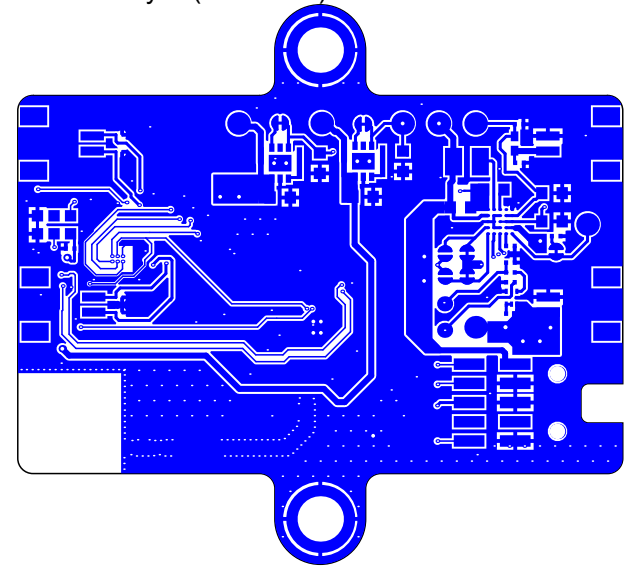
Int3 (SIG) (Scale 2:1)



Int4 (GND) (Scale 2:1)



Bottom Layer (Scale 2:1)

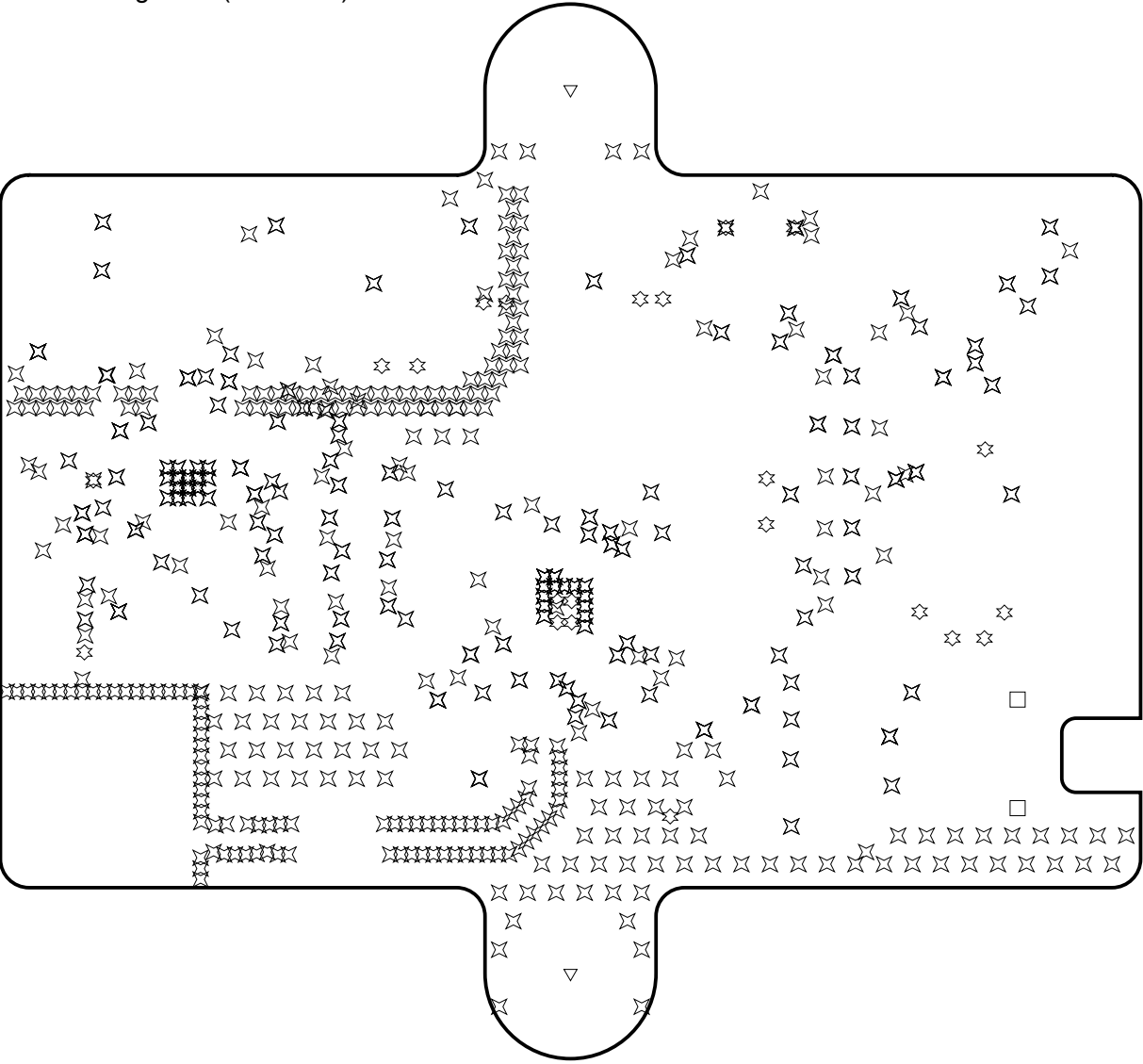


Drills

Drill Drawing View (Scale 4:1)

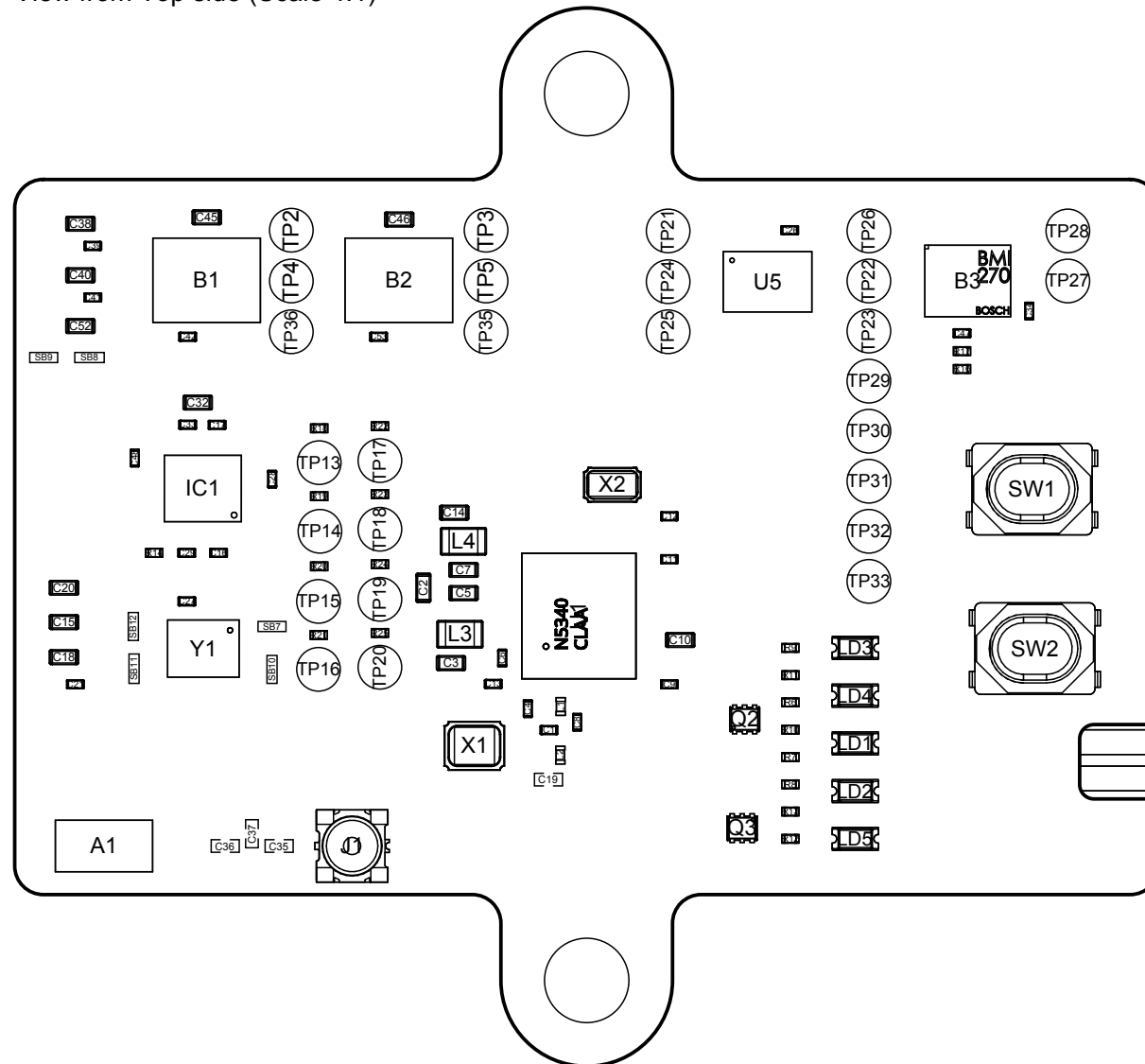
Drill Table

Symbol	Count	Hole Size	Plated	Hole Tolerance
✧	801	0.10mm	Plated	
☆	22	0.25mm	Plated	
□	2	1.02mm	Non-Plated	
▽	2	3.00mm	Plated	
	827 Total			



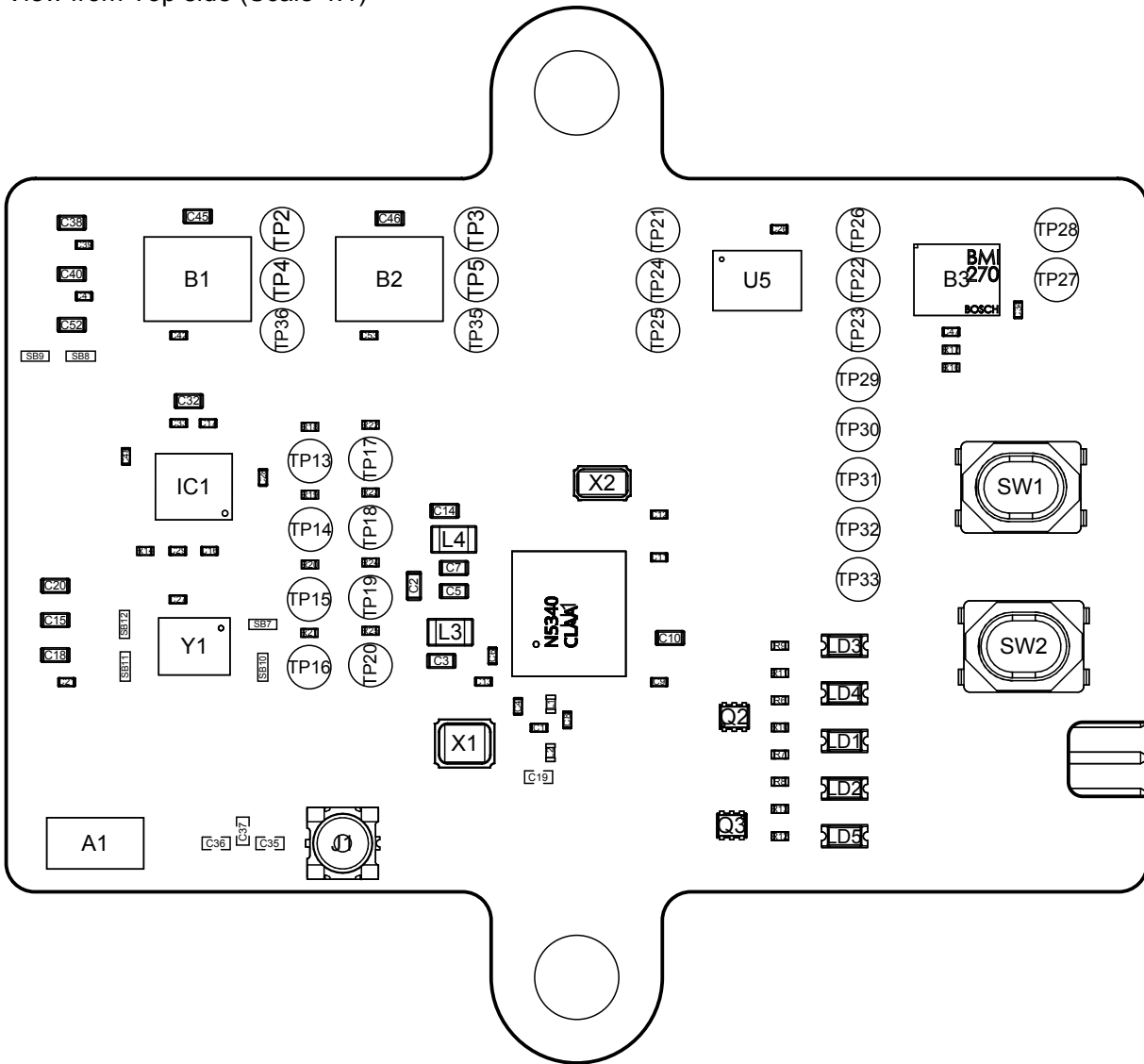
Assembly Top

View from Top side (Scale 4:1)



Assembly Bottom

View from Top side (Scale 4:1)

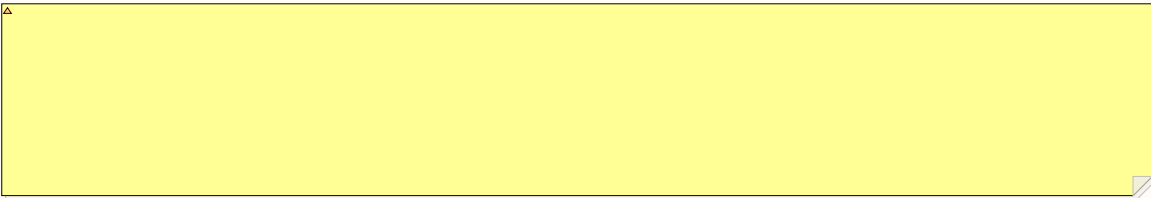


Metamaterials Group: Microwaves and Optics

Tiresias Hearing Device Prototype

Sheet 1:	Cover
Sheet 3:	MCU
Sheet 4:	Audio Codec
Sheet 5:	PMIC
Sheet 6:	Miscellaneous

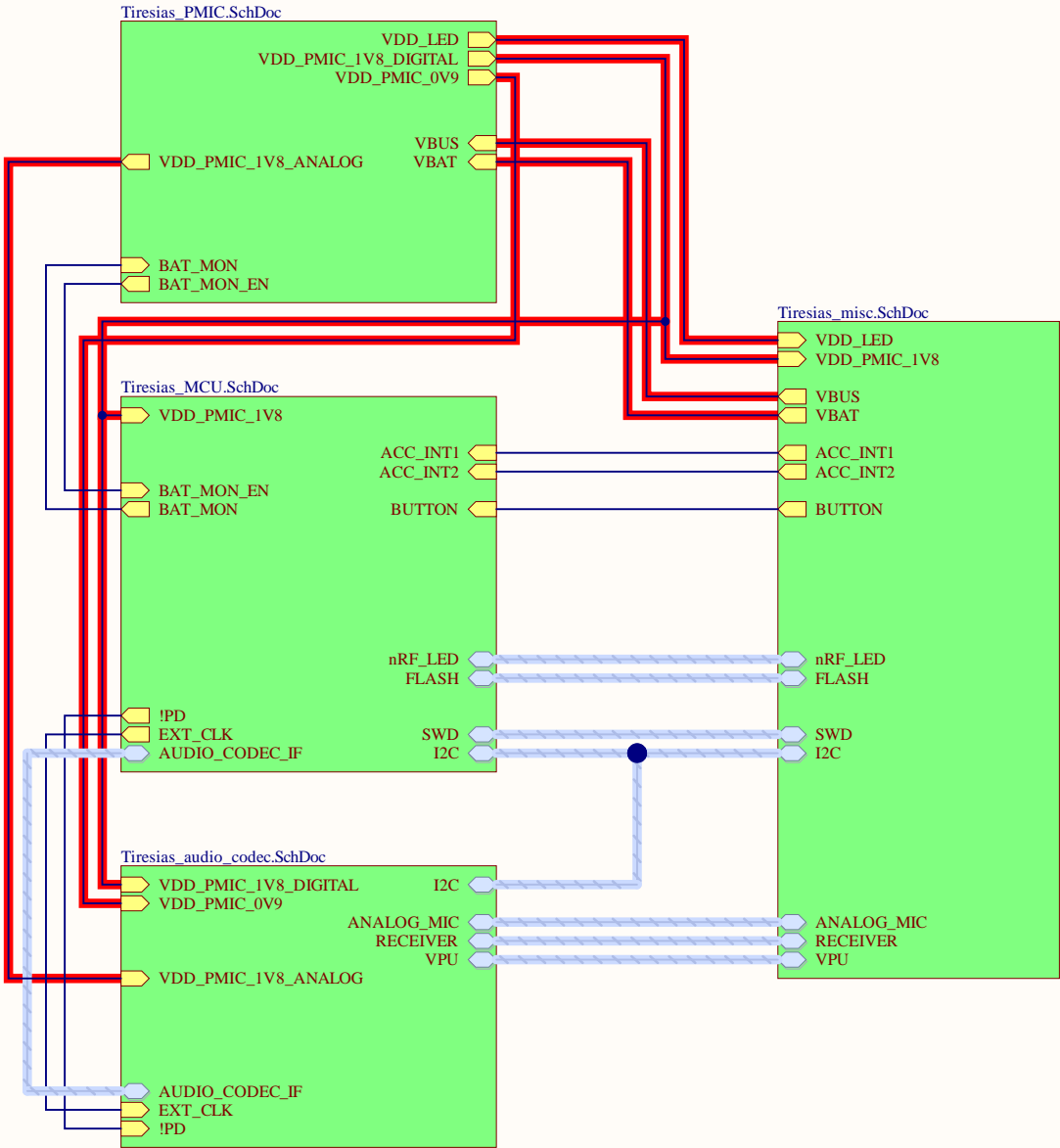
- Power Signals
- Analog Signals
- Serial Communication
- RF




✗ The No ERC object is a design directive.
This directive is placed on a node in the circuit to suppress reported warnings and/or error violation conditions that are detected when the schematic project is compiled.

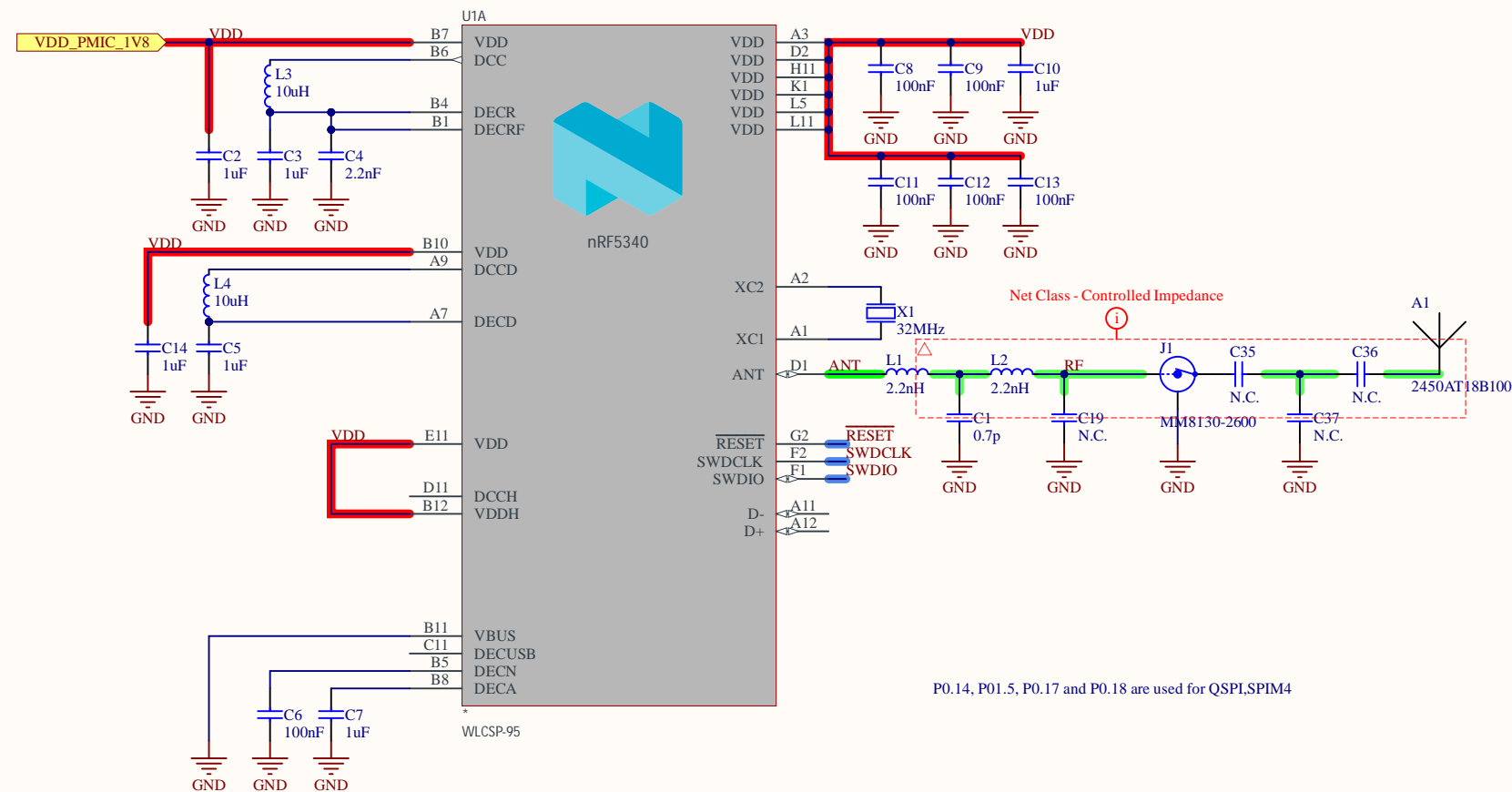
⚡ The DIFFPAIR object is a design directive.
This directive is placed on a differential pair so that they are routed accordingly.

These are fiducial marks



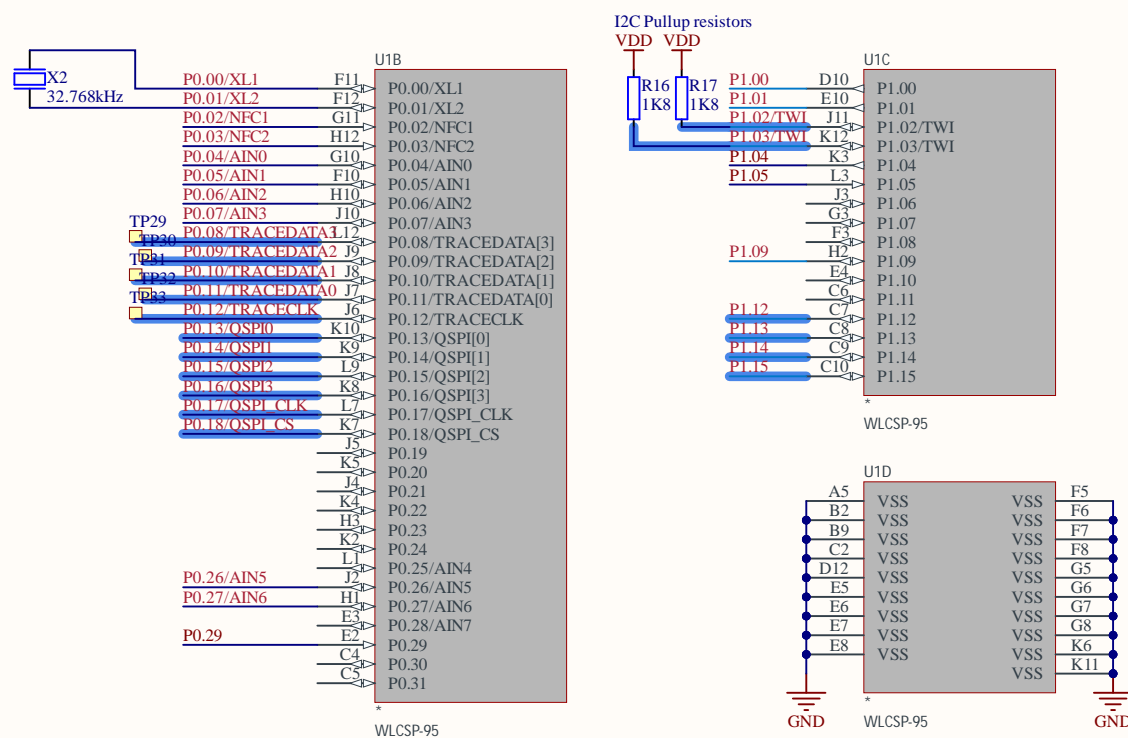
Title: Tiresias Cover Letter			<i>GMETA</i> <i>EESC - USP</i> <i>400, Trabalhador São-Carlense Av.</i> <i>13566-590, São Carlos</i> <i>São Paulo, Brazil</i>		
Drawn By: João Victor Colombari Carlet					
Size: A3	Number: *	Revision:0			
Date: 31/01/2025	Time: 16:25:36	Sheet 1 of 5	Website: http://www.sel.eesc.usp.br/jcarmo/metamaterials/		
File: C:\Users\Public\Documents\Altium\Tiresias\Tiresias_Cover_letter.SchDoc					

Nordic nRF52811 MCU



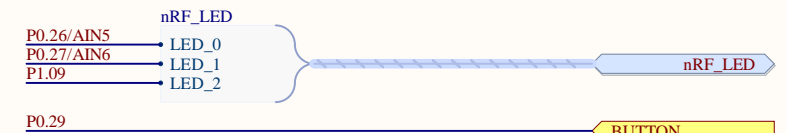
P0.14, P0.15, P0.17 and P0.18 are used for QSPI,SPIM4

MCU Peripherals

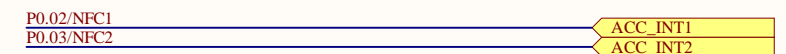


OBS

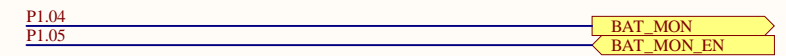
User Interface



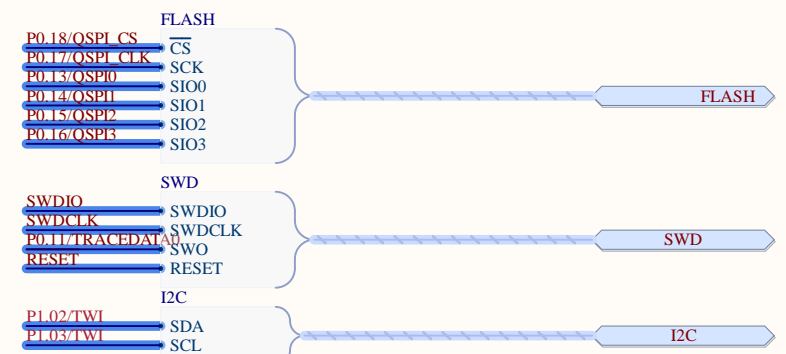
Accelerometer



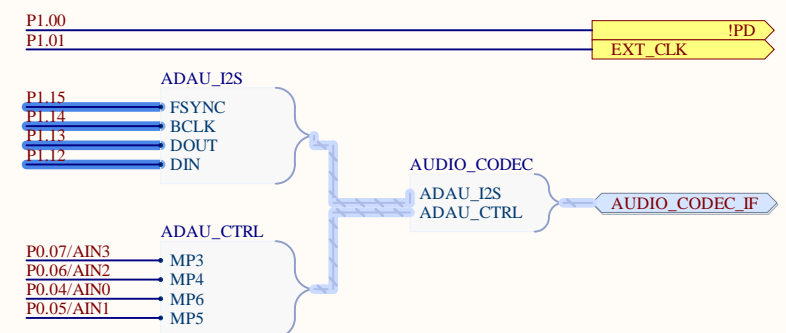
PMIC




Serial Communication



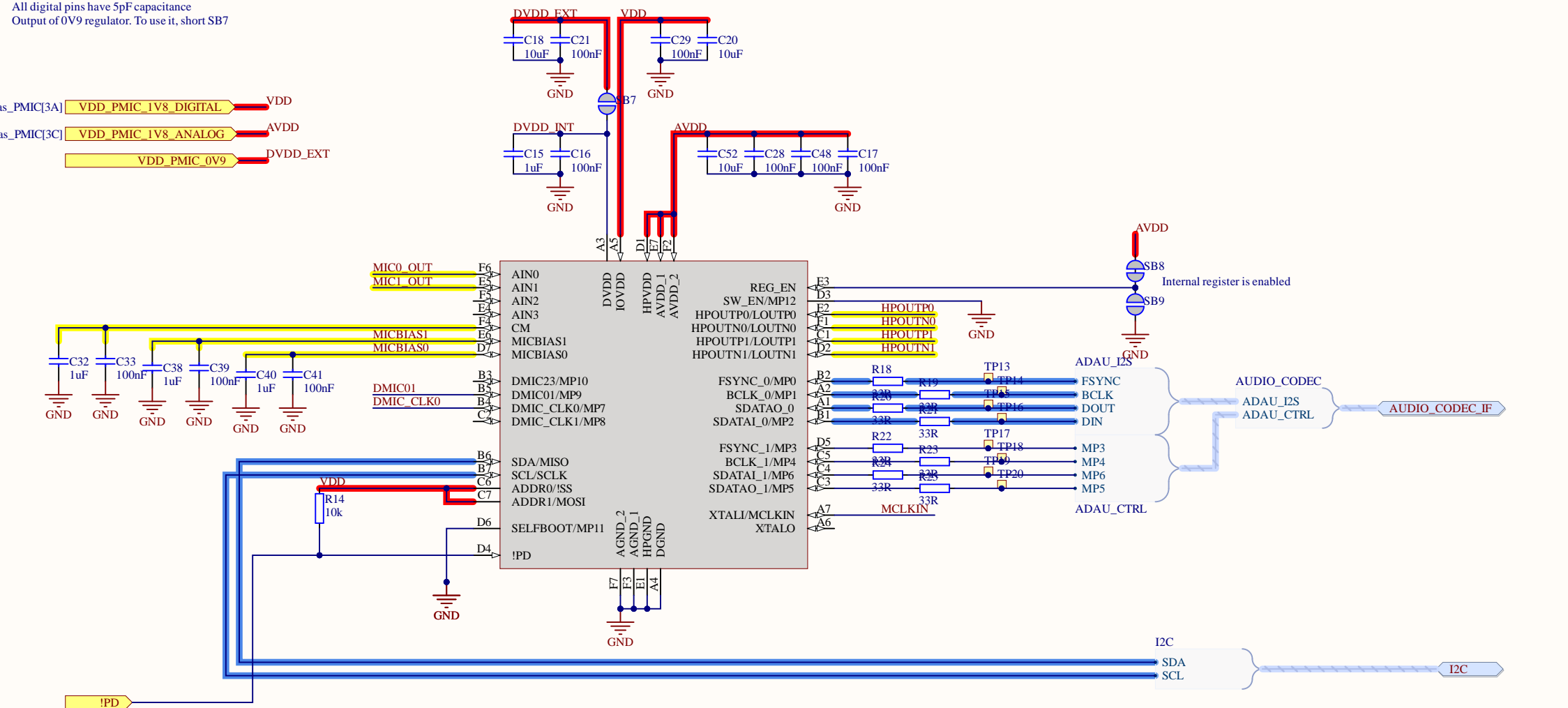
Audio Codec



Title: MCU			GMETA <i>EESC - USP</i> 400, Trabalhador São-Carlense Av. 13566-590, São Carlos São Paulo, Brazil	
Drawn By: João Victor Colombari Carlet				
Size: A3	Number: *	Revision: 0		
Date: 31/01/2025	Time: 16:25:36	Sheet 2 of 5	Website: http://www.sel.eesc.usp.br/jcarmo/metamaterials/	
File: C:\Users\Public\Documents\Altium\Tiresias\Tiresias_MCU.SchDoc				

Analog Devices ADAU1787 Audio Codec

All digital pins have 5pF capacitance
Output of 0V9 regulator. To use it, short SB7



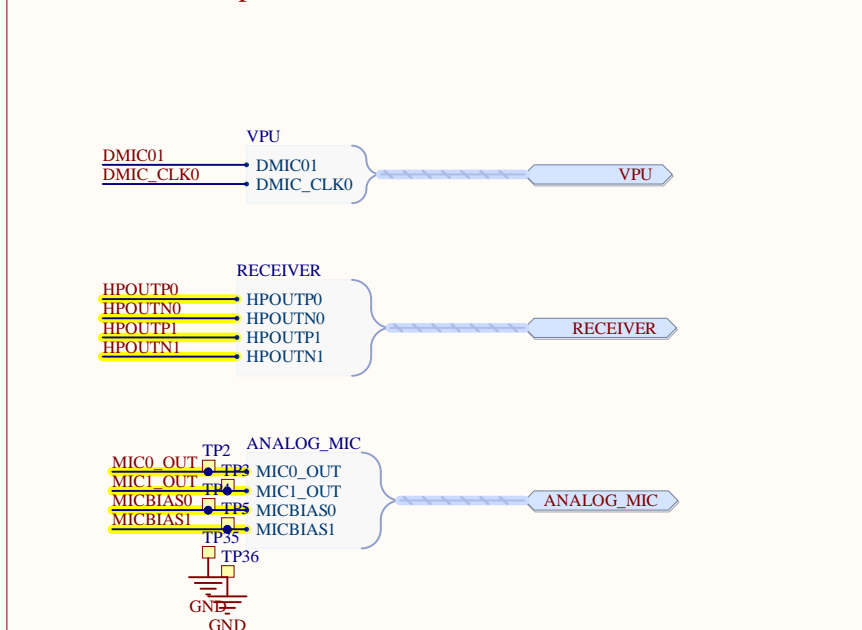
OBS

- For CLK use PWM from NRF. XTALO is open and crystal oscillator reg must be disabled
- REG_EN can be grounded to disable 0.9V LDO if DVDD is supplied
- Do not power up IOVDD when power is not applied to AVDD.
- I2C/SPI Enable (SW_EN). Connect this pin to DGND.

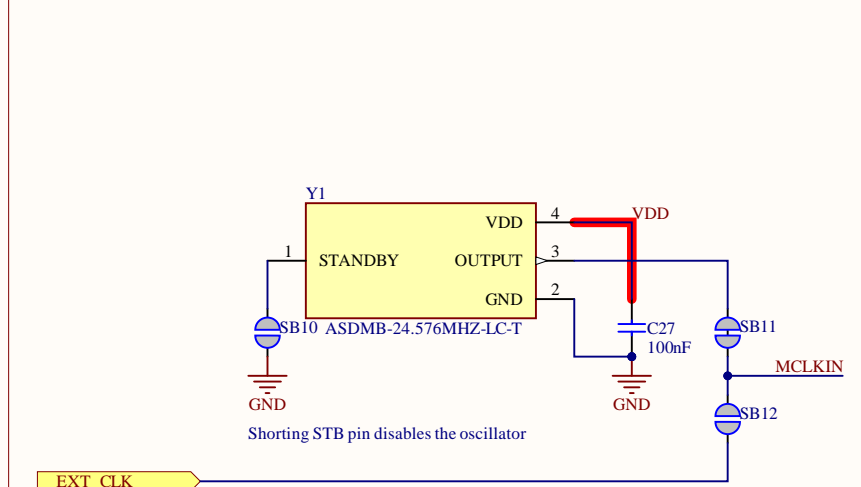
Configurations

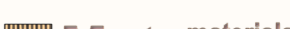
- Using two analog inputs with passives recommended by PUI audio. Do not forget to use a PUI with lower than 1.6V spec
- Bypassed power. DVDD is bypassed even if internal reg is used. IOVDD and AVDD are both connected to 1V8
- Falta a gravação com int e ext, mas por enquanto prefiro fazer com o interno. REG_EN - Regulator Enable. Tie this pin to AVDD to enable the regulator, and tie this pin to ground to disable the regulator. The IC can be put into I2C and/or SPI mode by tying the SW_EN pin to DGND
- CM bypassed. Could also be used for external amp common mode adjust
- Selfboot puts ADAU on master mode so that it boots using the EEPROM. Not used here
- PD control via microcontroller
- For the I2S remember to use compatible GPIO on the nordic side
- I2C addreses set to 0x2B with both ADDR0 and ADDR1 connected to IOVDD
- CLK
- DMIC connections for using one vesper VPU alone

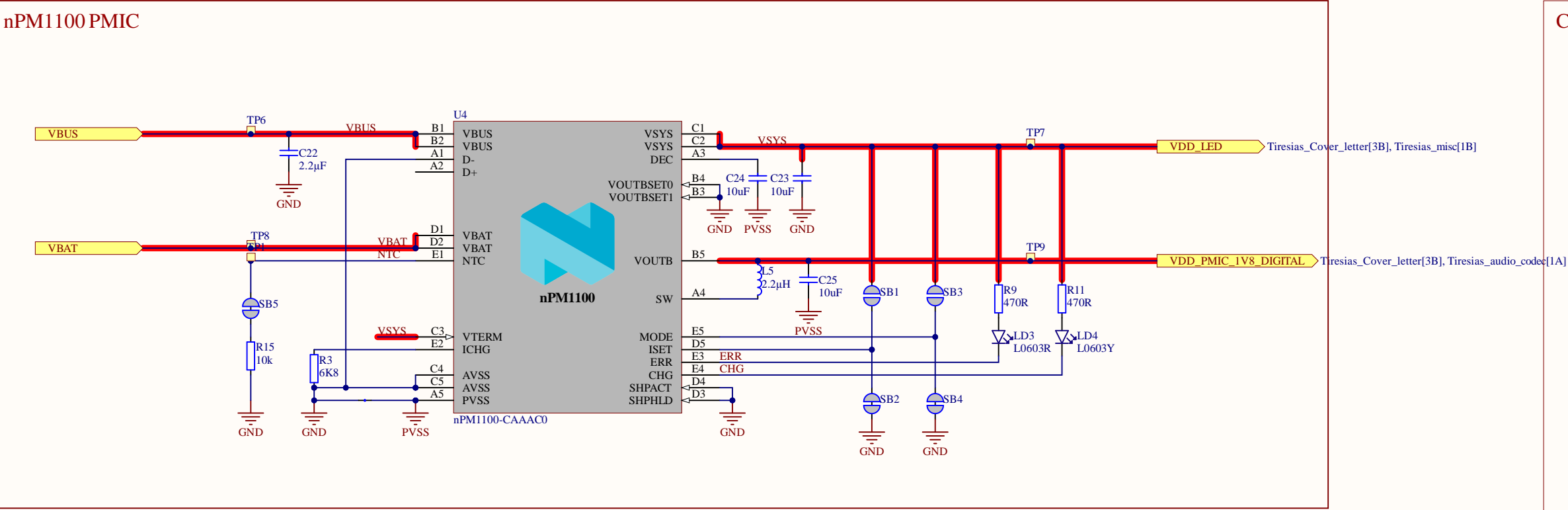
Audio Codec Peripherals



Audio Codec CLK

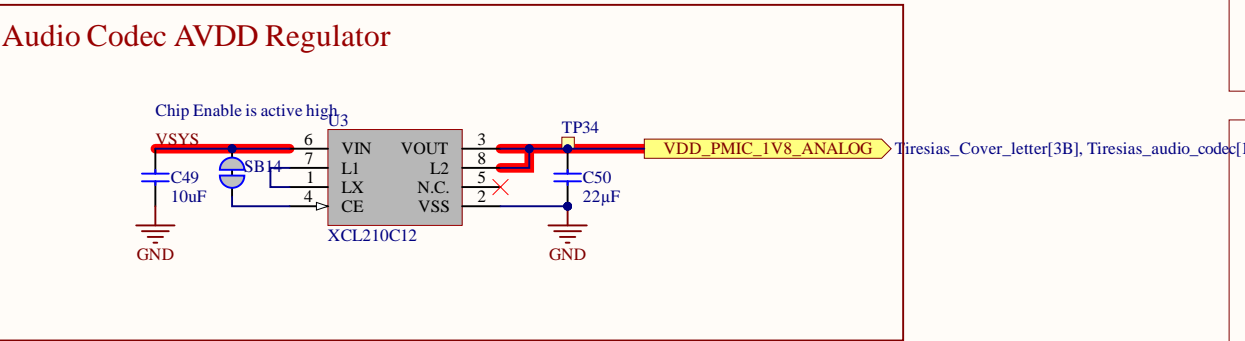
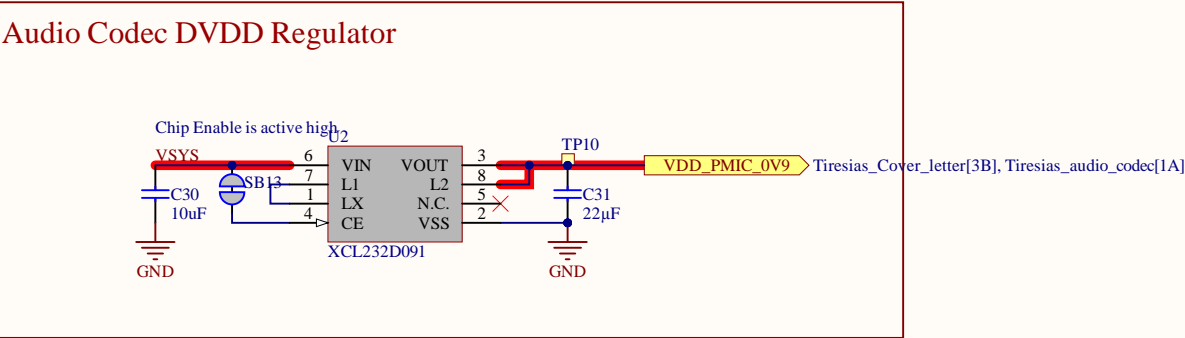
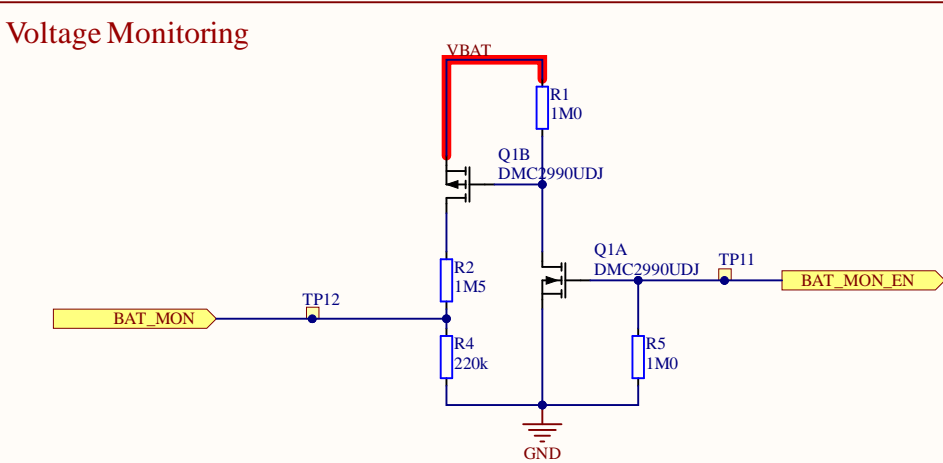


Title: Audio Codec			<i>R&D GMETA EESC - USP 400, Trabalhador São-Carlense Av. 13566-590, São Carlos São Paulo, Brazil</i>	
Drawn By: João Victor Colombari Carlet				
Size: A3	Number: *	Revision: 0	Website: http://www.sel.eesc.usp.br/jcarmo/metamaterials/	
Date: 31/01/2025	Time: 16:25:36	Sheet 3 of 5		
File: C:\Users\Public\Documents\Altium\Tiresias\Tiresias_audio_codec.SchDoc				



- ### Configurations
- For fixed VBUS current options:
D+=NC; D-=AVSS and either:
ISET=AVSS for 100mA or
ISET=VSYS for 500mA
 - VTERM high - 4.2V charge termination
- 3V7 Lilium or LiPo battery
 - RCHG = 625/current_limit-1562.5
For 6K8 resistor current is 75mA, which is right above 70mA for the min I found at mouser
 - Added NTC short and TP for external
 - Mode Low Automatic selection between Hysteretic and PWM modes. Since . In PWM mode, BUCK provides a clean supply operation, there are SB for an eventual change
 - VOUTBSET 0 and 1 to Low = 1V8 VOUTB output
 - If Ship mode is not required, then SHPACT and SHPHLD pins may be tied to AVSS.
 - NTC
10kR +- 15 at 25 Celcius
B25/50 constant 3380K
B25/85 constant 3434 to 3435K

If the thermal protection feature is not used, then a 10 kΩ, ≤20% accuracy resistor should be connected between NTC and AVSS pins.
 - An application should not be supplied directly from VBAT because it can disturb the battery charging process and may cause incorrect behavior from the charger. Instead, VOUTB and/or VSYS should be used to supply an application.

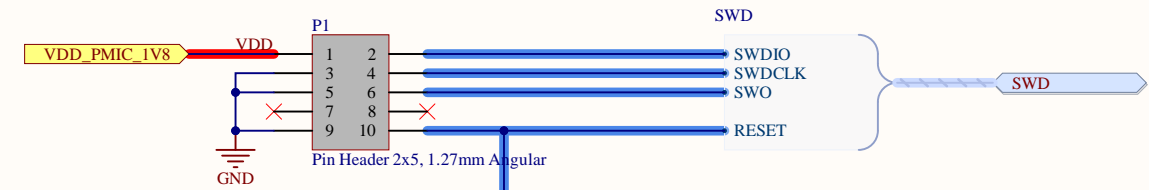


Reference

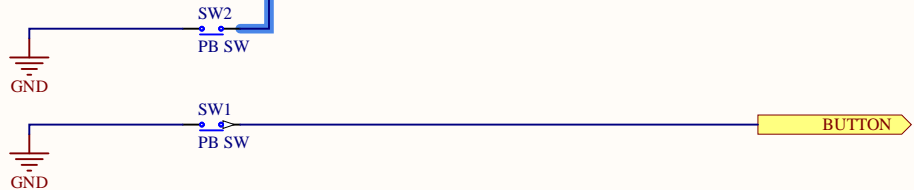
Cannot open file C:\Users\alunos\Desktop\reference.PNG. File does not exist.

- ### OBS
- The VDD pin allows the debugger (e.g., a programmer or debug probe) to detect the operating voltage of the target system. This ensures that the debugger can adjust its signal levels (for SWDIO and SWCLK) to match the target device's logic levels, preventing damage due to mismatched voltages. The VSYS and DEC pins must not be externally supplied
 - Product must have standard Vterm spec

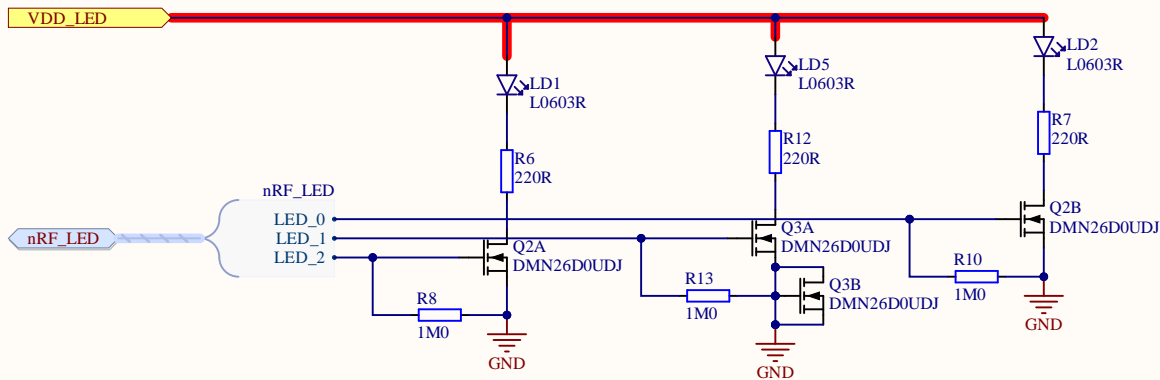
SWD Interface



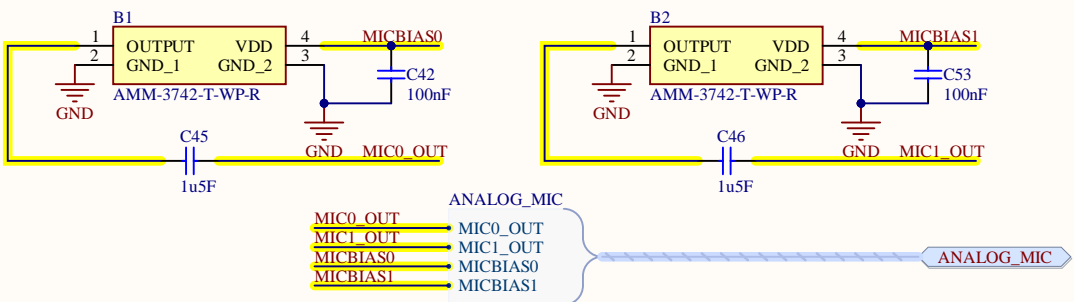
Push Button



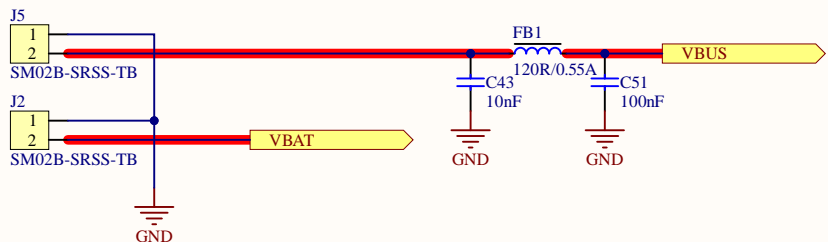
LEDs



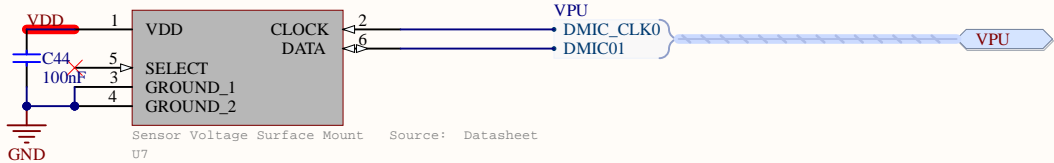
Analog Microphones



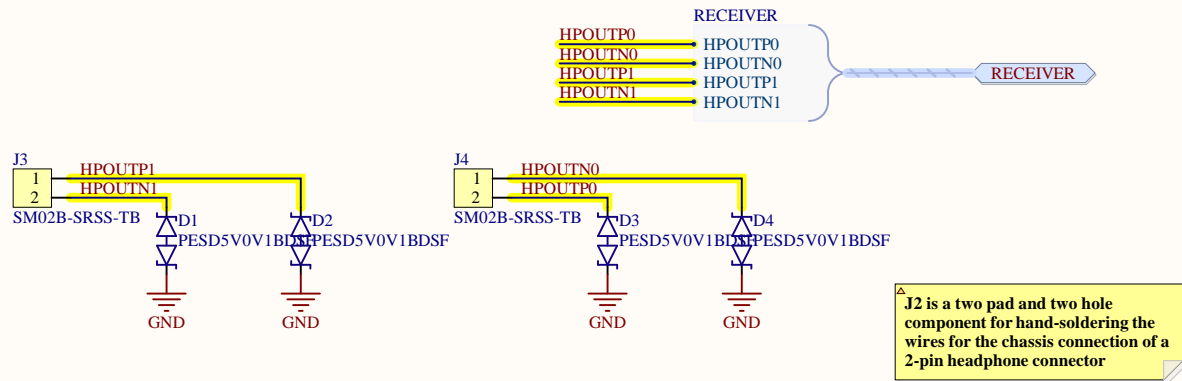
Power Connectors



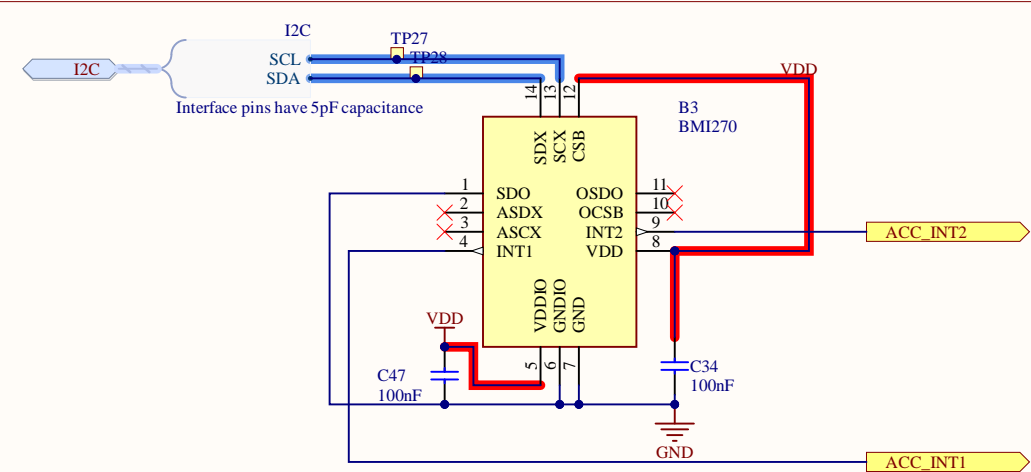
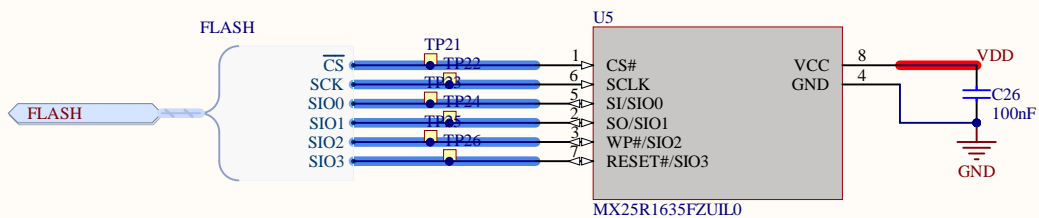
VPU



Receiver Connector



Flash Memory



ACC - The default I²C address of the device is 0b1101000 (0x68). It is used if the SDO pin is pulled to 'GND'. The alternative address 0b1101001 (0x69) is selected by pulling the SDO pin to 'VDDIO'.

CSB - Chip select for SPI mode. Connects to VDDIO**. ** DNC is also possible due to an internal pull-up, as long as the voltage never drops below VIH.

Comment	Description	Designator	Footprint	AltPart	Quantity
2450AT18B100	2.45 GHz chip antenna	A1	2450AT18B100	Johanson 2450AT18B100	1
AMM3742-T-WP-R	Microphones MEMS/CMUT - 42 DB 2VDC 200 uA 300 30mL20 Hz - 20kHz Analog Microphone MEMS (Silicon) 1.5 V -3.6 V Omnidirectional (-40dB +/-1dB) Solder Pads	B1, B2	AMM3742TWP-R	AMM3742-T-WP-R	2
BM270	BM270 - Inertial Measurement Units Smart Ultra-Low Power Inertial Measurement Unit (IMU) for Wearable Applications	B3	BM270	BM270	1
0.7p	Capacitor, NP0, ±2%	C1	CAPC06030038_C	CAP_0201_0p7	1
1uF	Capacitor, X5R, ±5%	C2, C3, C5, C7, C10, C14, C15, C32, C38, C40	CAPC1005X04L	CAP_0402_1uF	10
2.2nF	Capacitor, NP0, ±2%	C4	CAPC06030038_C	CAP_0201_2n2	1
100nF	Capacitor, NP0, ±2%	C6, C8, C9, C11, C12, C13, C16, C17, C21, C24, C27, C28, C29, C33, C34, C39, C41, C42, C44, C47, C48, C51, C53	CAPC06030038_C	CAP_0201_100nF	23
10uF	Capacitor, X5R, ±5%	C18, C20, C52	CAPC1005X04L	CAP_0402_10uF	3
N/C	Capacitor, NP0, ±2%	C19, C35, C36, C37	CAPC06030038_C_NC	CAP_0201_NC	4
2.2uF	Capacitor, Ceramic, X5R, ±10%, 10V	C22	CAPC1608X06L	CAP_0603_2u2F	1
10uF	Capacitor, X5R, ±10%	C23, C24, C25, C30, C49	CAPC1608X06L	CAP_0603_10uF	5
22uF	Capacitor, X5R, ±20%, 6.3V	C31, C50	CAPC1608X06L	CAP_0603_22uF	2
10nF	Capacitor, NP0, ±2%	C43	CAPC06030038_C	CAP_0201_10nF	1
1uF	Capacitor, X5R, ±5%	C45, C46	CAPC1005X04L	CAP_0402_1uF	2
PESD50V018DSF	Very low capacitance bidirectional ESD protection diode	D1, D2, D3, D4	DFN40P40X30-2N	PESD50V018DSF	4
120R/0.55A	Ferrite Bead, 120 Ohm @ 100kHz, 500mA, 250 mOhm Max	FB1	INDC1005X04L	FB0402-120R@100MA 500mA	1
General Purpose Audio Codec 48K/1.2DAC Ch 42-Pin WLCSP 17R Source: Datasheet		IC1	BCGA4C39F7K6_270R 232K3	ADAU1768BCR0L	1
NWBT30-2600	Coaxial Connector with Switch	J1	COAXIAL-SWF	NWBT30-2600	1
SM02B-SR5S-TB	1.5mm pitch connector side entry SMD	J2, J3, J4, J5	SM02B-SR5S-TB(LF)(SN)	SM02B-SR5S-TB	4
2.2nH	High frequency chip inductor ±5%	L1, L2	INDC06030038_C	IND_0201_2n2H	2
10uH	Chip inductor, IDC_min - 50 mA, ±20%	L3, L4	INDC1608X06L	IND_0603_10uH	2
2.2uH	FIXED IND 2.2uH 2.5A 80mOhm SMD	L5	INDC2016K10N	IND_0806_2u2H	1
LD602R	LED, SMD, 0603, RED	L01, L02, L03, L05	LED_0603_R	LED_0603_RED	4
LD062Y	LED, Yellow, 0603, 590nm, Vf=2.0V, 120mA - 400u - 85°C	L04	LED_0603_Y	LED_0603_YEL	1
Pin Header 2x5, 1.27mm Angular	Pin Header 2x5, 1.27mm (50mil), SMD, Keying Shroud Acetate	P1	HDR_2x5-SMD-1.27mm-ANG	Pin Header 2x5 SMD, 1.27mm, ANG	1
DMC2990UDJ	MOSFET, Dual N and P Channel, 20V, 450mA/710mA, 950mOhm, 350mW	Q1	SOITL3SF100K50-6N	DMC2990UDJ-7	1
DMN2600UDJ	MOSFET, Dual N Channel, 20V, 240mA, 1050mOhm, 300mW	Q2, Q3	SOITL3SF100K50-6N	DMN2600UDJ-7	2
1M0	Resistor, ±1%, 0.05W	R1, R5, R8, R10, R13	RES06030038_C	RES_0201_1M0	5
1M5	Resistor, ±1%, 0.05W	R2	RES06030038_C	RES_0201_1M5	1
4K8	Resistor, ±1%, 0.05W	R3	RES06030038_C	RES_0201_4K8	1
220K	Resistor, ±1%, 0.05W	R4	RES06030038_C	RES_0201_220K	1
220R	Resistor, ±1%, 0.05W	R6, R7, R12	RES06030038_C	RES_0201_220R	3
470R	Resistor, ±1%, 0.05W	R9, R11	RES06030038_C	RES_0201_470R	2
10K	Resistor, ±1%, 0.05W	R14, R15	RES06030038_C	RES_0201_10K	2
1K8	Resistor, ±1%, 0.05W	R16, R17	RES06030038_C	RES_0201_1K8	2
33R	Resistor, ±1%, 0.05W	R18, R19, R20, R21, R22, R23, R24, R25	RES06030038_C	RES_0201_33R	8
P8 SW	Tactile Switch, SPNO, SMD, 160uF, 4.2x3.3x2.5mm	SW1, SW2	KL5-TS3401	KL57-TS3401-2.5-160R	2
	Multi-protocol Bluetooth Low Energy, IEEE 802.15.4, ANT and 2.4GHz proprietary system-on-chip	U1	BGA95C39F12X11_43 7X97X50	HRFS340-CLAA	1
XC1232D091	0.9V Ultra-Low Quiescent Current, Inductor Built-in Step Down DC/DC Converter, CL-2025-03 Source: Datasheet	U2	CL-2025	XC1232D091K8-G	1
XC1210C12	1.8V, 200mA Inductor Built-in Step Down "micro DC/DC" Converter	U3	CL-2025	XC1210C18	1
HPM1100-CAAACD	Li-Ion/Li-Polymer USB battery charger with a high efficiency buck regulator	U4	BGA25C40PXS_200K 200X50	HPM1100-CAAACD	1
MX25R1635FZJUL0	Wide Vcc Range 16M-BIT (x 1x 2x 2x 4) 2Mx2 KIOXAND (SERIAL MULTI I/O) FLASH MEMORY	U5	USON-8L 2X3X0P6_JMAC-L	MX25R1635FZJUL0	1
Sensor Voltage Surface Mount Source: Datasheet		U7	V25200D18	V25200D-1-8	1
320kHz	XTAL SMD 2016, 320kHz, Cl=8pF, Total Tol: ±50ppm	X1	BT-XTAL_2016	XTAL_SMD2016_32M Hz	1
32.768kHz	XTAL SMD 2012, 32.768kHz, Cl=8pF, Total Tol: ±50ppm	X2	XTAL_2012	XTAL_SMD2012_32k7 68Hz	1
AS0MB-24.576MHz-LC-T		Y1	XTAL_AS0MB-24.576MHz-LC-T	AS0MB-24.576MHz-LC-T	1